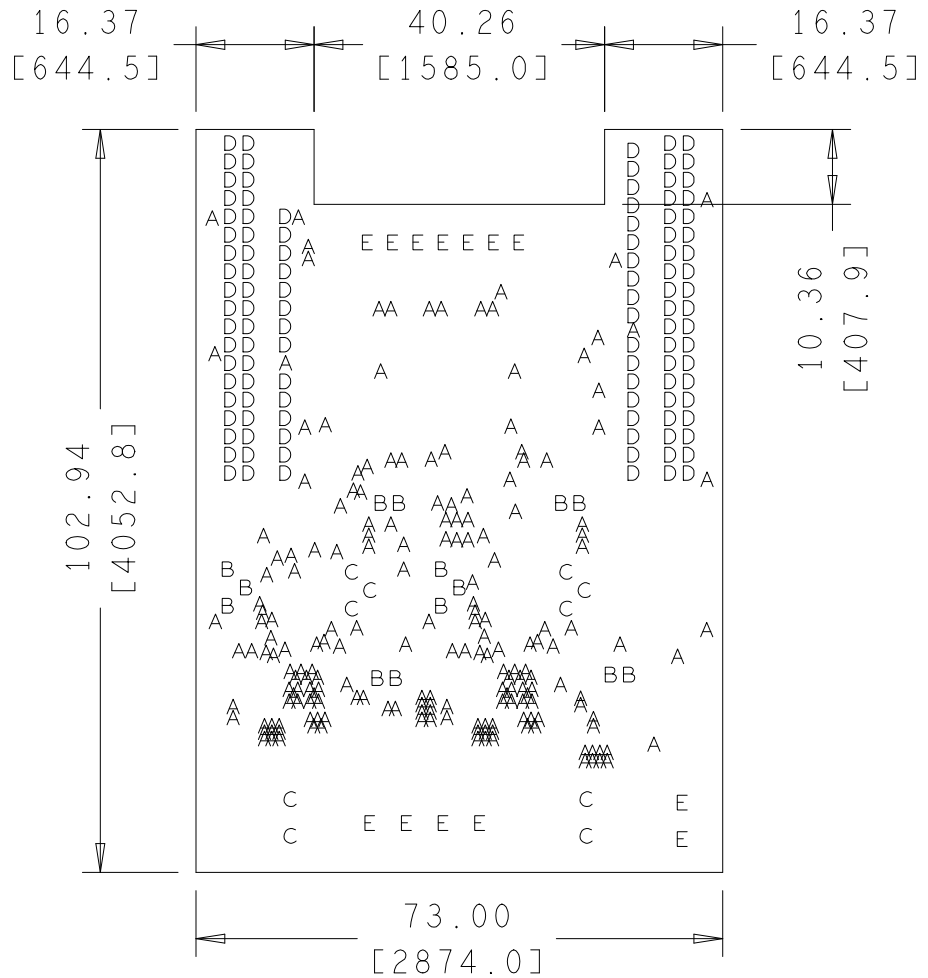
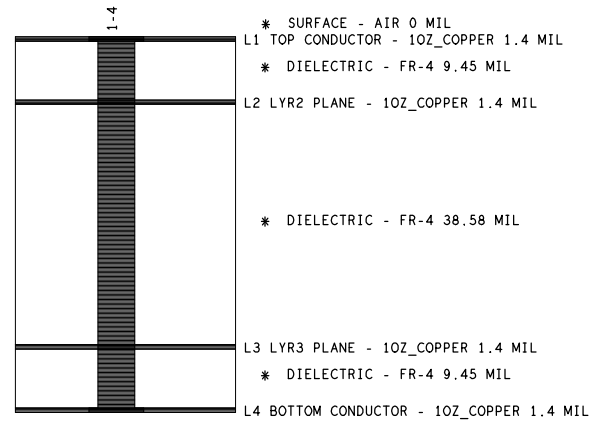


Finished Hole Tolerance - All units are in Inches -		
Finish Hole Diameter	Plated Through Finish Hole Diameter	Non Plated Through Finish Hole Diameter
0.008"-0.013"	+0.002/-FHS"	+/-0.002"
0.014"-0.063"	+/-0.003"	+/-0.002"
0.064"-0.156"	+/-0.004"	+/-0.003"
0.157"-0.250"	+/-0.007"	+/-0.004"
0.251"and up	+/-0.007"	+/-0.005"
0.125"	Non Plated Only	+0.003/-0.000"

DETAIL 'A'



DESIGN CROSS SECTION CHART
TOTAL THICKNESS 63.08 MIL

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED_SIZE	PLATED	QTY
A	12.0	PLATED	196
B	35.43	PLATED	14
C	39.37	PLATED	10
D	44.0	PLATED	108
E	55.0	PLATED	13
	TOTAL HOLES:		341

FABRICATION NOTE:

1:FABRICATE USING LATEST REVISION OF IPC-6012B CLASS 2 OR ABOVE
2:FABRICATE USING MASTER ARTWORK EVLSPIN99 R1 FOR CIRCUIT PATTERN
NO DEVIATION FROM MASTER ARTWORK ARE PERMITTED WITHOUT WRITTEN APPROVAL FROM AN AUTHORIZED STM REPRESENTATIVE
3:VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH APPROPRIATE VENDOR UL IDENTIFICATION MARK, LOT OR JOB NUMER AND PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
4:MATERIAL: FR4 RoHS COMPLIANT MINIMUM 170 C
SEE "DETAIL "A"" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
5:SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE PER IPC-SM-840 (LATEST LEVEL), CLASS H. COLOR: BLUE
6:FINISH: ENIG Au>0.05u 3u<Ni<5u
7:FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF OF SOLDER MASK IS ALLOWED
8:SILKSCREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
9:THIS IS NOT A CONTROLLED IMPEDANCE BOARD
10:DESIGNATED AREA OR INSPECTION AND TEST STAMP
11:ON PCB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE
(MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
12:VENDOR TO PROVIDE BOARD STACK-UP AND IMPEDANCE (IF REQUIRED) APPROVAL PRIOR TO BOARD FABBRICATION.STACK UP AND IMPEDANCE (IF REQUIRED) TO INCLUDE COPPER PLATING ON OUTER LAYERS.FAB DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY
VENDOR TO PROVIDE BOARD FOR IMPEDANCE TEST RESULTS AND COUPON (IF REQUIRED)
13:TEARDROPPING OF VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
14:REMOVE SILKSCREEN FROM SOLDERABLE SURFACE
15:ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND SHORTS. APPLY TEST STAMP IN REFERENCED AREA
16:THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796

REVISION DATE

ASP, AMS Group ITALY

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Drawn: M. Rigo — date: 19-Jan-2024
Approved — date

Description: EVLSPIN99
DRILLING AND PROFILING

Symbol: EVLSPIN99
Group

TOLERANCE UNLESS NOTED
UNIT=MM

	0 <10	>10 <50	>50 <200	>200	ANG. LES.
linear					
midle	±0.1	±0.2	±0.3	±0.5	±1°
accurate	±0.05	±0.1	±0.15	±0.25	±30°

ISO | SCALE: 1 : 1 | REV. 1.0

Material

Treatment and surface finishing